Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP t610 PLUS Thin Client

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC battery on Main Board</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps N/A</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Adapter cable, Power cord</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
</tbody>
</table>

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### Components and waste containing asbestos
- N/A
- 0

### Components, parts and materials containing refractory ceramic fibers
- N/A
- 0

### Components, parts and materials containing radioactive substances
- N/A
- 0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Socket wrench (For disassemble 4 pcs screws on rear I/O connector)</td>
<td>5mm 3.00-6.00kgf.cm</td>
</tr>
<tr>
<td>Description #2 Philips screw drivers (a. For disassemble 2 pcs screws on rear I/O assembly) (b. For disassemble 4pcs screws on MB, 3pcs for HDD cage.)</td>
<td>2# 3.00-6.00kgf.cm</td>
</tr>
<tr>
<td>Description #4 Philips screw driver (For disassemble thermal module and blower)</td>
<td>T15# 3.00-6.00kgf.cm</td>
</tr>
<tr>
<td>Description #4 Philips screw driver (For disassemble 2 pcs screws on the speaker)</td>
<td>1# 3.00-6.00kgf.cm</td>
</tr>
<tr>
<td>Description #5 Philips screwdriver (For disassemble 2pcs screw for Wireless card)</td>
<td>T4 0.70-1.00kgf.cm</td>
</tr>
</tbody>
</table>

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the bottom cover, please refer the figure.1.
2. Remove the side panel for both sides, please refer the figure.2.
3. Remove the access panel, please refer the figure.3.
4. Remove the graphic card, please refer the figure.4.
5. Remove the fly cable head on riser card, then remove the riser card, please refer the figure.5.
6. Remove the 4pcs hex screws for COM port and DVI, please refer the figure.6.
7. Remove the two screws for real IO assembly, then disassemble the real IO assy from base pan, please refer the figure.7.
8. Remove the blower head on PCB, then disassemble the blower on heat sink, please refer the figure.8.
9. Remove the thermal module, please refer the figure.9.
10. Remove the PATA module, please refer the figure.10.
11. Remove the antenna cables from Mini PCI-e CARD and speaker head on PCB, please refer the figure.11.
12. Remove the two screws for Wireless card on PCB, then disassemble the wireless card from PCB, please refer the figure.12.
13. Remove the memory, please refer the figure.13.
14. Remove the HDD drive, please refer the figure.14.
15. Remove the 3pcs screws from HDD cage and 4pcs screws on PCB, please refer the figure.15.
16. Remove the MB, please refer the figure.16.
17. Remove the front bezel, please refer the figure.17.
18. Remove the top cover, please refer the figure.18.
19. Remove the two antennas on chassis vertical top side and bottom side, please refer the figure.19.
20. Remove the two screws for speaker, then remove the speaker from base pan, please refer the figure.20.
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

![Figure 1](image1)

![Figure 2](image2)

![Figure 3](image3)

![Figure 4](image4)

![Figure 5](image5)

![Figure 6](image6)

![Figure 7](image7)

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Figure 8
Figure 9
Figure 10
Figure 11
Figure 12
Figure 13
Figure 14
Figure 15
Figure 16

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